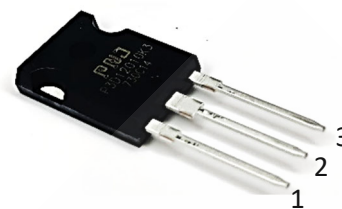


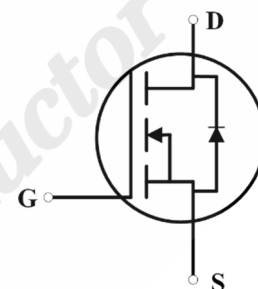
SiC MOS P3M12120K3

N-Channel Enhancement Mode



Features

- Qualified to AEC-Q101
- High Blocking Voltage with Low On-Resistance
- High-Frequency Operation
- Ultra-Small Q_{gd}
- 100% UIS tested



Benefits

- Improve System Efficiency
- Increase Power Density
- Reduce Heat Sink Requirements
- Reduction of System Cost

TO-247-3

Gate	1
Drain	2
Source	3

Application

- Solar Inverters
- EV Battery Chargers
- High Voltage DC/DC Converters
- Switch Mode Power Supplies



Order Information

Part number	Package	Marking
P3M12120K3	TO-247-3	P3M12120K3



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P3M12120K3 SiC MOS N-Channel Enhancement Mode

1. Maximum Ratings

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value	Unit	Test Conditions
Drain - Source Voltage	V_{DSmax}	1200	V	$V_{GS} = 0V$ $I_D = 100\mu A$
Gate - Source Voltage (dynamic)	V_{GSmax}	-8 / +21	V	AC ($f > 1\text{Hz}$)
Gate - Source Voltage(static) turn-on gate voltage turn-off gate voltage	$V_{GS,on}$ $V_{GS,off}$	+18 -3	V	Static
Continuous Drain Current	I_D	25	A	$V_{GS} = 18V$ $T_C = 25^\circ\text{C}$
		19		$V_{GS} = 18V$ $T_C = 100^\circ\text{C}$
Power Dissipation	P_D	100	W	
Operating Junction	T_J	-55 To +175	$^\circ\text{C}$	
Storage Temperature	T_{stg}	-55 To +175	$^\circ\text{C}$	
Solder Temperature	T_L	260	$^\circ\text{C}$	
Mounting Torque	M_d	1 8.8	Nm lbf-in	M3 or 6-32 screw



P3M12120K3 SiC MOS N-Channel Enhancement Mode

2. Electrical Characteristics

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1200	/	/	V	$V_{GS} = 0V$ $I_D = 100\mu A$
Gate Threshold Voltage	$V_{GS(th)}$	1.8	2.4	/	V	(tested after 30ms pulse at $V_{GS} = 18V$) $V_{DS} = V_{GS}$ $I_D = 2.5mA$ $T_J = 25^\circ\text{C}$
		/	1.6	/	V	$V_{DS} = V_{GS}$ $I_D = 2.5mA$ $T_J = 175^\circ\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}	/	1	100	μA	$V_{GS} = 0V$ $V_{DS} = 1200V$
Gate-Source Leakage Current	I_{GSS}	/	20	250	nA	$V_{GS} = 18V$ $V_{DS} = 0V$
Drain-Source On-State Resistance	$R_{DS(on)}$	/	120	156	m Ω	$V_{GS} = 18V$ $I_D = 10A$ $T_J = 25^\circ\text{C}$
		/	172	/		$V_{GS} = 18V$ $I_D = 10A$ $T_J = 175^\circ\text{C}$
Transconductance	g_{fs}	/	8	/	S	$V_{DS} = 20V$ $I_{DS} = 10A$ $T_J = 25^\circ\text{C}$

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
		/	6	/		V _{DS} = 20V I _{DS} = 10A T _J = 175°C
Input Capacitance	C _{iss}	/	1032	/	pF	V _{GS} = 0V V _{DS} = 800V f = 1MHz V _{AC} = 25mV
Output Capacitance	C _{oss}	/	38.7	/		
Reverse Transfer Capacitance	C _{rss}	/	4.2	/		
Coss Stored Energy	E _{oss}	/	15.8	/	μJ	
Turn-on Energy	E _{on}	/	232	/	μJ	V _{DS} = 800V V _{GS} = -3/18V I _D = 10A R _G = 1Ω
Turn-off Energy	E _{off}	/	15	/		
Turn-On Delay Time	t _{d(on)}	/	13.6	/	ns	V _{DS} = 800V V _{GS} = -3/18V I _D = 10A R _G = 1Ω
Rise Time	t _r	/	20.2	/		
Turn-Off Delay Time	t _{d(off)}	/	19.0	/		
Fall Time	t _f	/	32.6	/		
Internal Gate Resistance	R _{G(int)}	/	1.3	/	Ω	f = 1MHz V _{AC} = 25mV
Gate to Source Charge	Q _{gs}	/	11.9	/	nC	V _{DS} = 800V V _{GS} = -3/18V I _{DS} = 10A I _G = 20mA
Gate to Drain Charge	Q _{gd}	/	20.5	/		



P3M12120K3 SiC MOS N-Channel Enhancement Mode

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Total Gate Charge	Q_g	/	39.2	/		

3. Reverse Diode Characteristics

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value		Unit	Test Conditions
		Typ.	Max.		
Diode Forward Voltage	V_{SD}	5.9	/	V	$V_{GS} = -3\text{V}$ $I_{SD} = 5\text{A}$ $T_J = 25^\circ\text{C}$
		5.2	/	V	$V_{GS} = -3\text{V}$ $I_{SD} = 5\text{A}$ $T_J = 175^\circ\text{C}$
Continuous Diode Forward Current	I_S	15	/	A	$V_{GS} = -3\text{V}$
Reverse Recover Time	t_{rr}	25	/	ns	$V_{GS} = -3\text{V}$ $I_{SD} = 20\text{A}$ $V_R = 800\text{V}$ $dI/dt = 3600\text{A}/\mu\text{s}$ $T_J = 25^\circ\text{C}$
Reverse Recovery Charge	Q_{rr}	293	/	nC	
Peak Reverse Recovery Current	I_{rrm}	17	/	A	

4. Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Case	$R_{\theta JC}$	1.36	$^\circ\text{C}/\text{W}$

5. Typical Performance

At $T_J = 25^\circ\text{C}$, unless specified otherwise

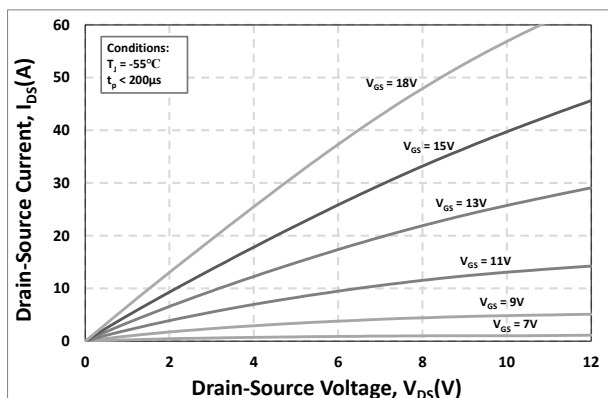


Figure 1. Output Characteristics $T_J = -55^\circ\text{C}$

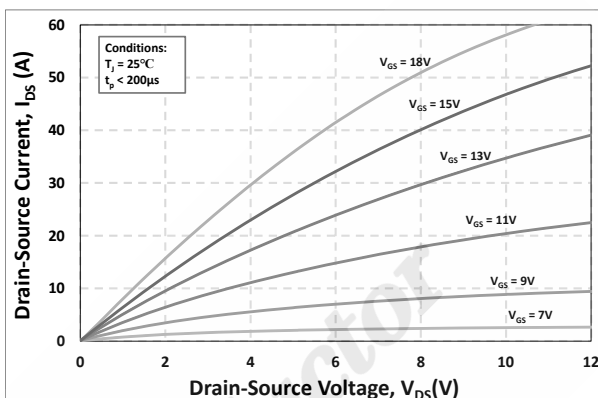


Figure 2. Output Characteristics $T_J = 25^\circ\text{C}$

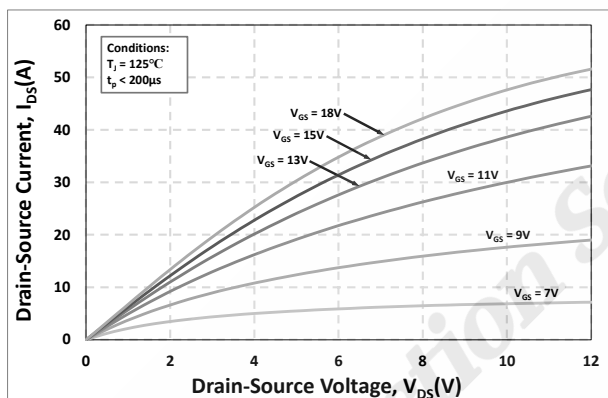


Figure 3. Output Characteristics $T_J = 125^\circ\text{C}$

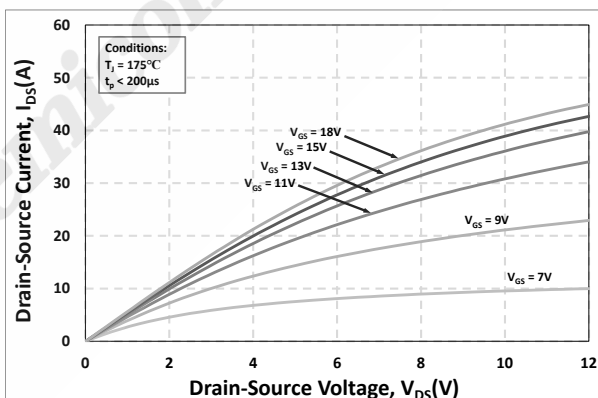


Figure 4. Output Characteristics $T_J = 175^\circ\text{C}$

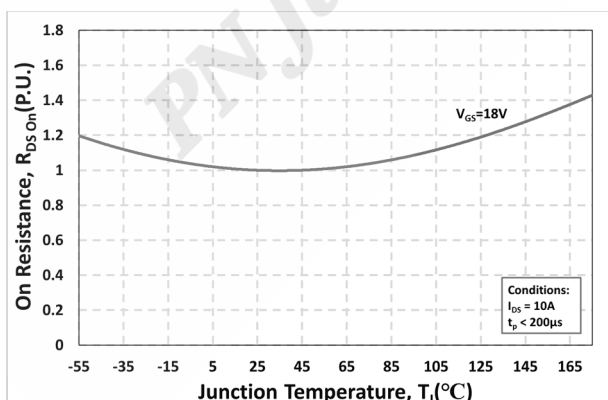


Figure 5. Normalized On-Resistance vs. Temperature

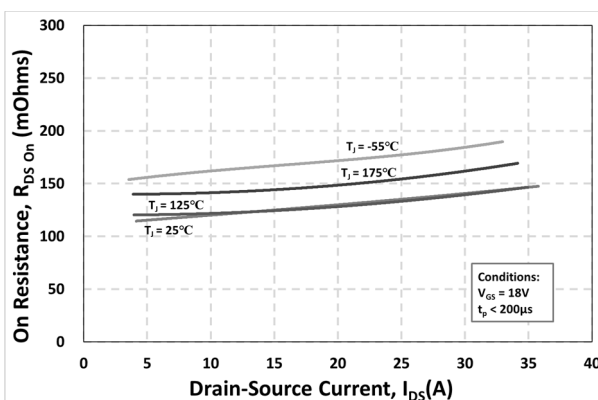


Figure 6. On-Resistance vs. Drain Current Various Temperatures

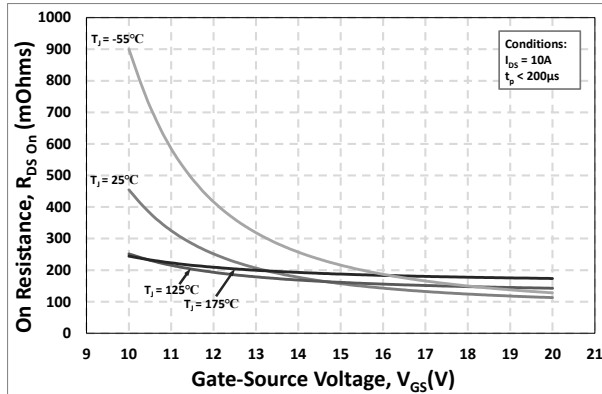


Figure 7. On-Resistance vs. Gate-Source Voltage

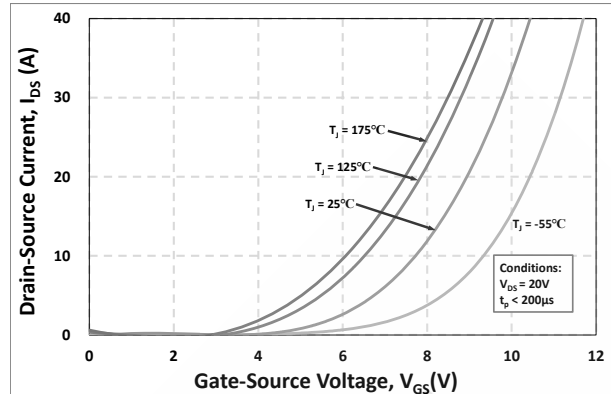


Figure 8. Transfer Characteristic for Various Junction Temperatures

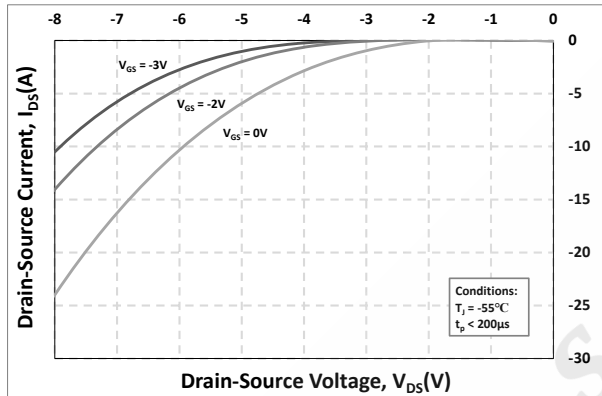


Figure 9. Body Diode Characteristic at -55°C

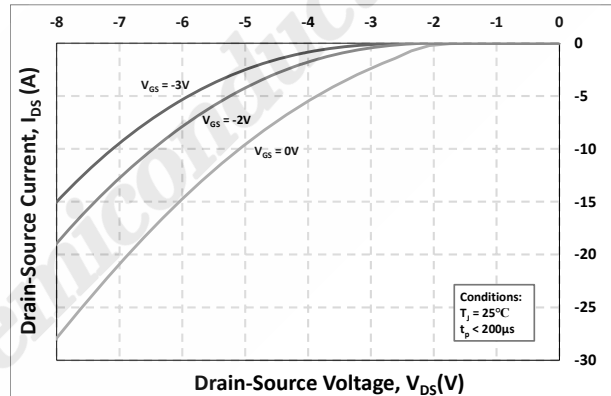


Figure 10. Body Diode Characteristic at 25°C

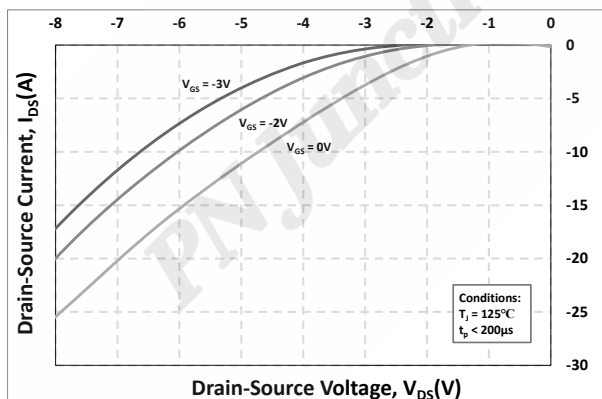


Figure 11. Body Diode Characteristic at 125°C

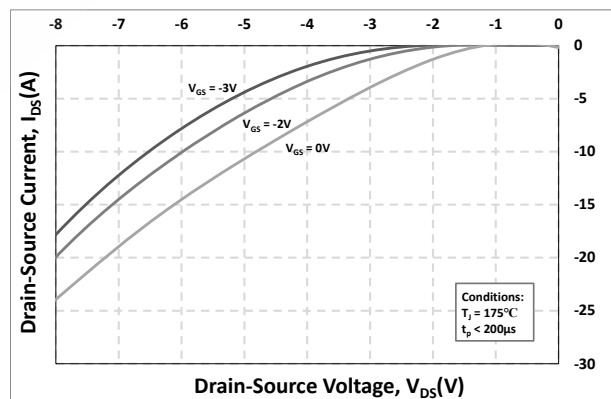


Figure 12. Body Diode Characteristic at 175°C

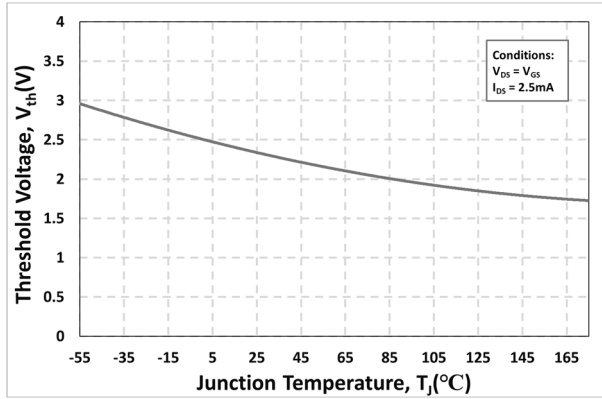


Figure 13. Threshold Voltage vs. Temperature

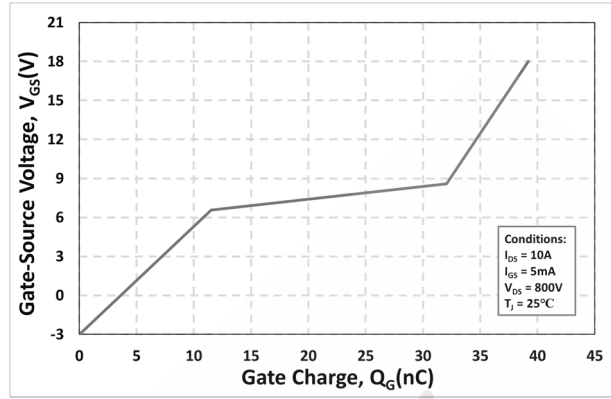


Figure 14. Gate Charge Characteristics

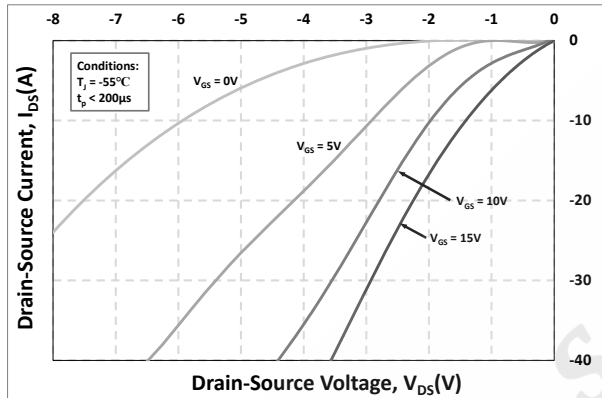


Figure 15. 3rd Quadrant Characteristic at $-55^\circ C$

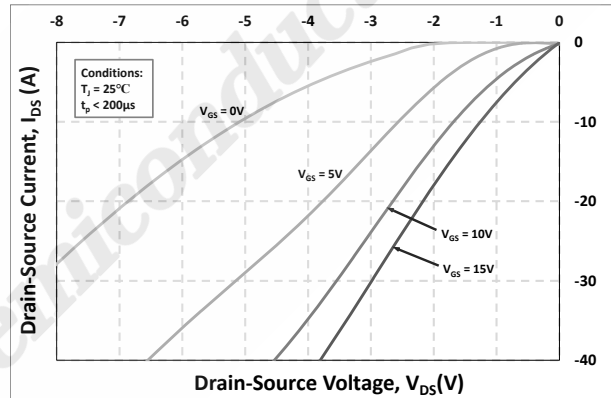


Figure 16. 3rd Quadrant Characteristic at $25^\circ C$

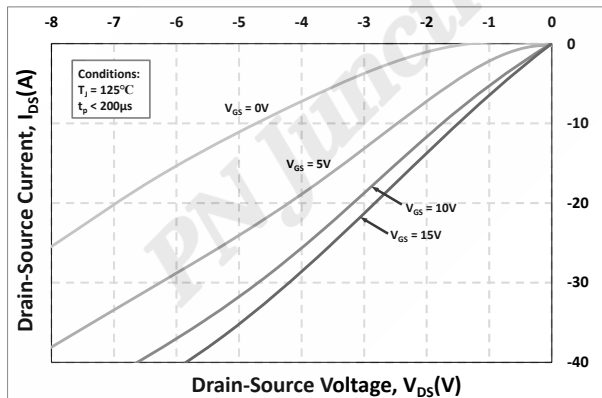


Figure 17. 3rd Quadrant Characteristic at $125^\circ C$

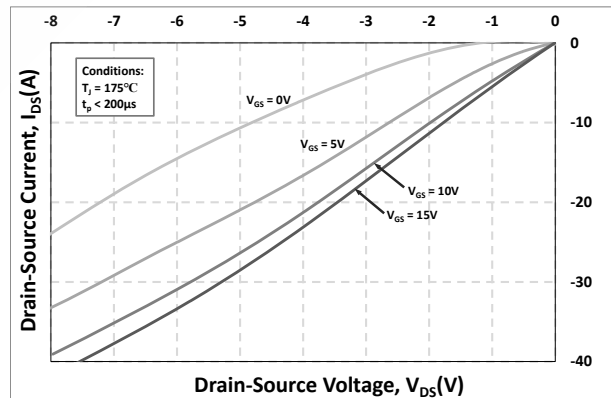


Figure 18. 3rd Quadrant Characteristic at $175^\circ C$

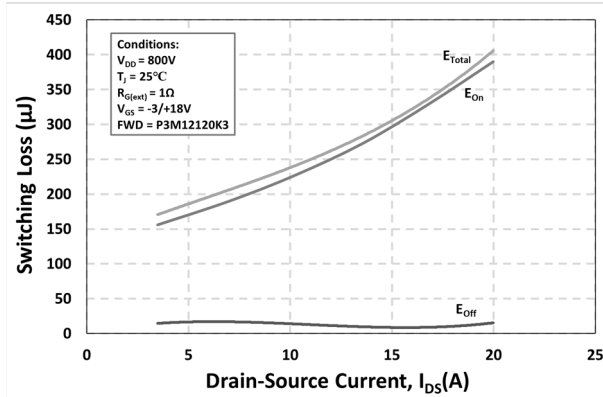


Figure 19. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 800V$)

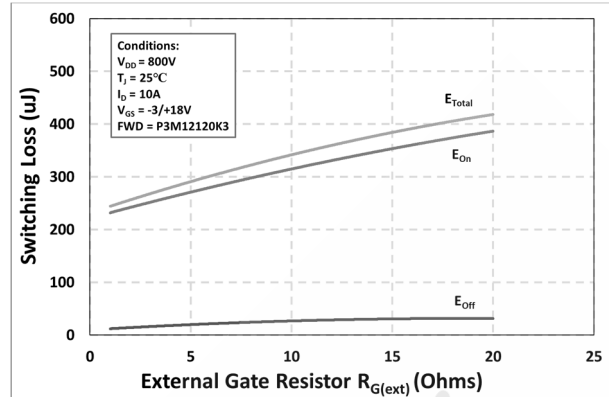


Figure 20. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

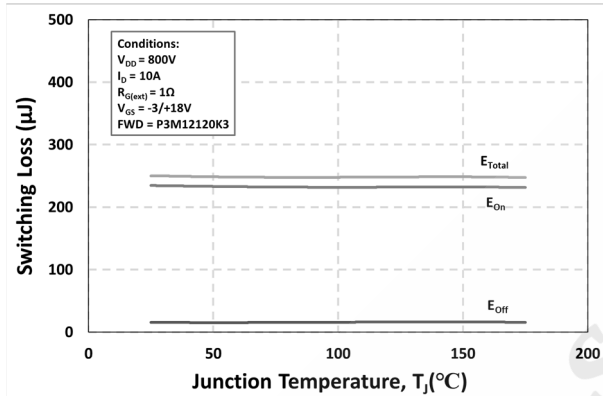


Figure 21. Clamped Inductive Switching Energy vs. Temperature

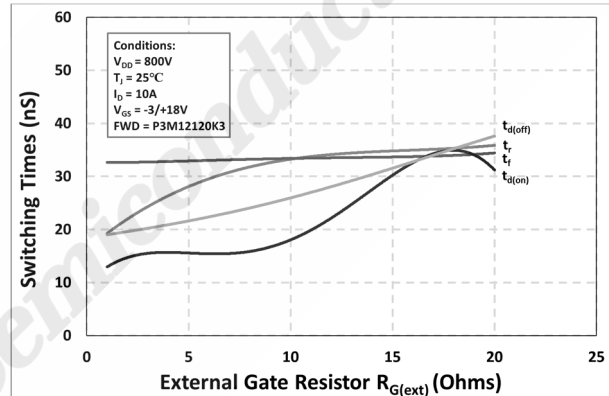


Figure 22. Switching Times vs. $R_{G(ext)}$

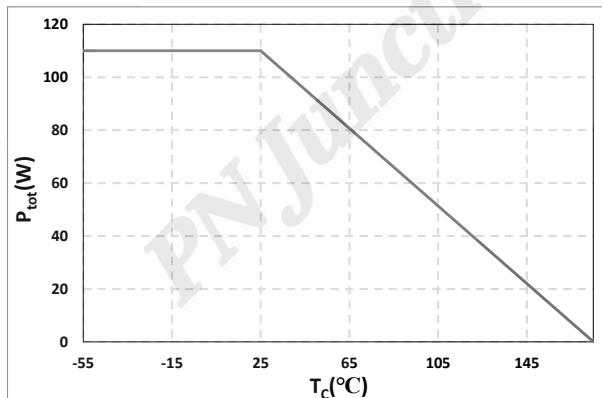


Figure 23. Maximum Power Dissipation Derating vs. Case Temperature

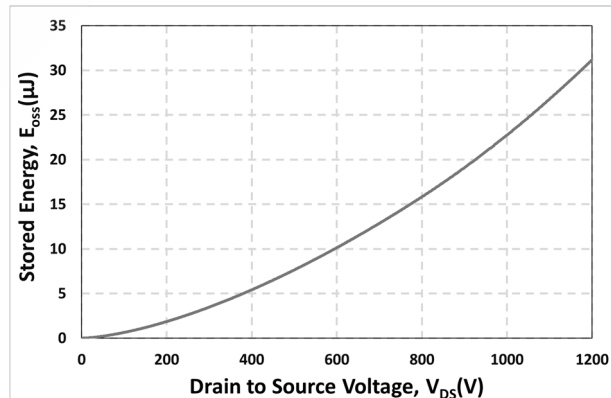


Figure 24. Output Capacitor Stored Energy

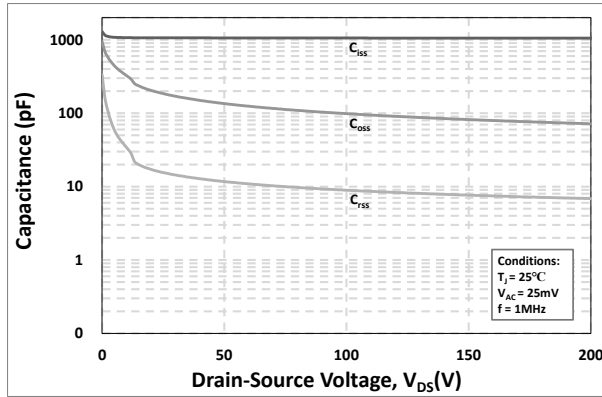


Figure 25. Capacitances vs. Drain-Source Voltage (0 - 200V)

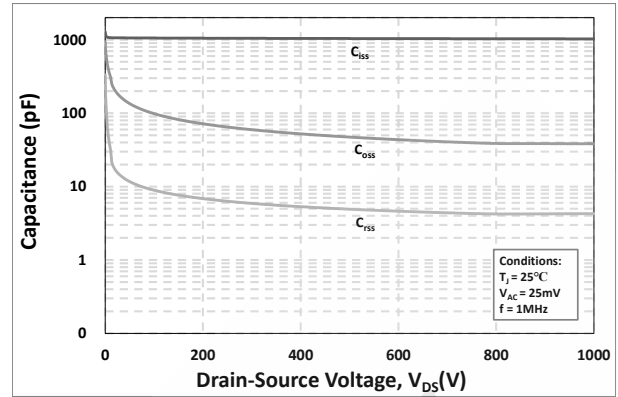


Figure 26. Capacitances vs. Drain-Source Voltage (0 - 1000V)

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6. Definitions

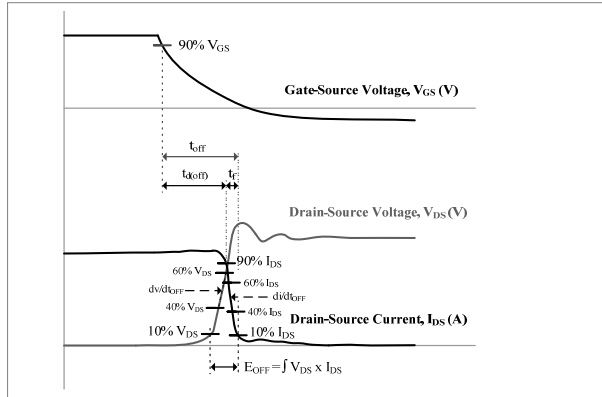


Figure 27. Turn-off Transient Definitions

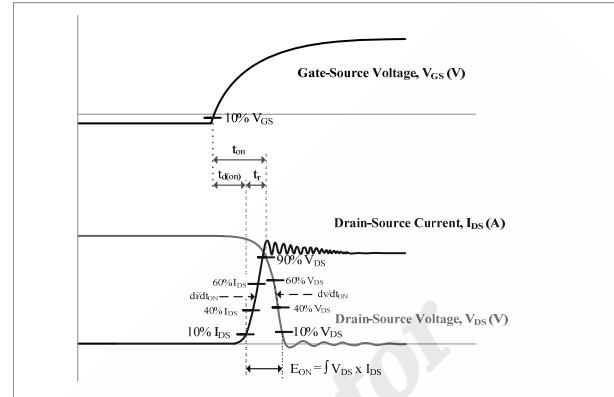


Figure 28. Turn-on Transient Definitions

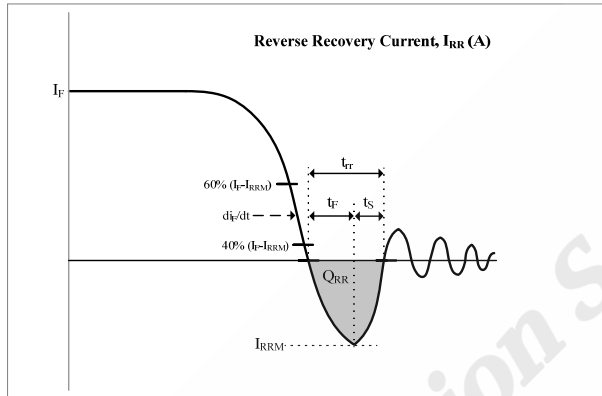


Figure 29. Reverse Recovery Definitions

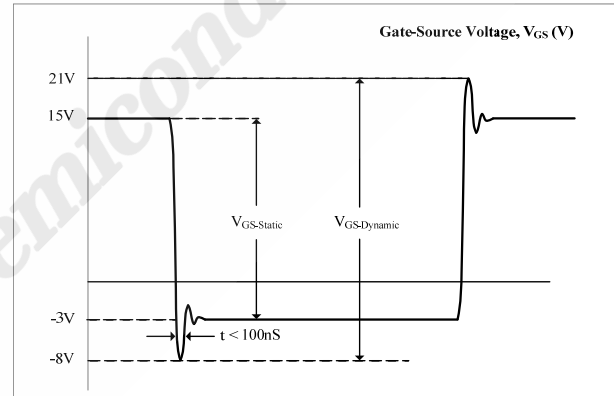
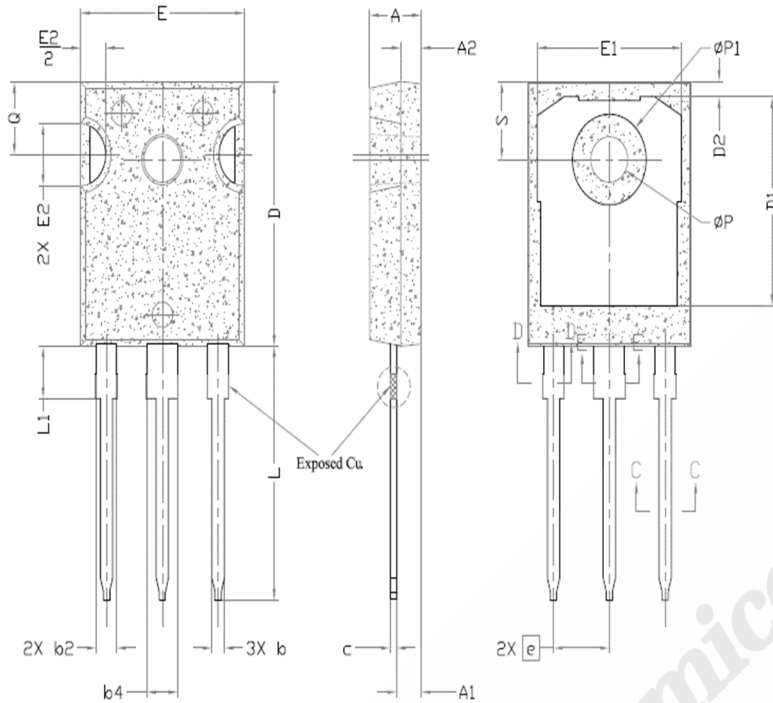


Figure 30. v_{gs} Transient Definitions

7. Package Outlines



SYMBOL	DIMENSIONS			NOTES
	MIN.	NOM.	MAX.	
A	4,83	5,02	5,21	
A1	2,29	2,41	2,55	
A2	1,50	2,00	2,49	
b	1,12	1,20	1,33	
b1	1,12	1,20	1,28	
b2	1,91	2,00	2,39	6
b3	1,91	2,00	2,34	
b4	2,87	3,00	3,22	6, 8
b5	2,87	3,00	3,18	
c	0,55	0,60	0,69	6
c1	0,55	0,60	0,65	
D	20,80	20,95	21,10	4
D1	16,25	16,55	17,65	5
D2	0,51	1,19	1,35	
E	15,75	15,94	16,13	4
E1	13,46	14,02	14,16	5
E2	4,32	4,91	5,49	3
e	5,44BSC			
L	19,81	20,07	20,32	
L1	4,10	4,19	4,40	6
ϕP	3,56	3,61	3,65	7
$\phi P1$	7,19REF.			
Q	5,39	5,79	6,20	
S	6,04	6,17	6,30	

Drawing and Dimensions



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